Y-201TS -LM

High Tg, White Laminate for package substrates & Prepreg

产品特点：

- ●无卤素，Tg220℃（DMA）
- ●高白度、高反射率
- ●优异的耐黄变性能
- ●厚度均匀性控制技术
- ●适用无铅制程
- ●优异的尺寸稳定性
- ●低膨胀和优异的通孔可靠性

应用领域：

封装载板、CMOS 传感器、摄像机等。

Key Features:

- ●Halogen Free and Tg220℃(DMA)
- ●High whiteness and high reflectivity
- ●Excellent yellowing resistance
- ●Thickness uniformity control technology
- ●Lead free process compatible
- ●Excellent dimensional stability
- ●Low Z-axis CTE and excellent through hole reliability

Applications:

Package substrate ,CMOS sensor, VCR.etc.

General properties

Item	Condition	Units	Typical value
玻璃化转变温度 Glass Transition Temperature	DMA	℃	220
白度 Whiteness	Internal standard	%	87.8
X,Y 轴方向膨胀系数 X,Y-CTE	TMA	ppm/℃	9～10
剥离强度 Peel Strength（Hoz Copper Foil）	288℃/10s	N/mm	1.3
层间结合力 Interlayer bond strength	A	N/mm	0.9
热失重(weight loss 5%) Decomposition temperature	TGA	℃	380
浸锡测试 Solderability	288℃	s	＞300
288℃分层时间 T288	TMA	min	＞60
热导率 Thermal conductivity	ASTM-D5470	W/(m*k)	0.7
吸水率 Moisture Absorption	D-24/23	%	0.13

Specimen thickness：0.4mm or 0.8mm. Test Method is according to IPC TM-650